

IN THE SPECIFICATION:

The specification as amended below with replacement paragraphs shows added text with underlining and deleted text with ~~striketrough~~.

Please AMEND the paragraph beginning spanning pages 1-2, as follows:

The dielectric layer is preferably burned at the temperature substantially higher than the softening point of the glass material. However, if it is burned at the temperature approximately 100 degrees centigrade higher than the softening point, flow of the glass may cause a pattern collapse of the colored glass layer, diffusion of the coloring agent into the dielectric layer resulting in deterioration of transparency of the dielectric layer, or color change of the coloring agent resulting failure in obtaining desired coloring effect. Therefore, conventionally, the composition of the glass material of the dielectric layer is selected so that the softening point becomes a relatively high temperature (e.g., 570 degrees centigrade), so that the burning is performed at [the] a temperature (e.g, 590 degrees centigrade) that is near to the softening point. In addition, in order to obtain a good dielectric layer, a thin dielectric layer is formed on the colored glass layer using a glass material having high softening point, and then, a material having low softening point (e.g., 490 degrees centigrade) is used and is burned at substantially high temperature so that the dielectric layer having a necessary thickness can be formed. The thin dielectric layer can prevent the ~~deform~~ deformation of the colored glass layer and the diffusion of the coloring agent.

Please AMEND the paragraph spanning pages 5-6, as follows:

Fig. 1 is a perspective view showing the inner structure of the plasma display panel according to the present invention. In this figure, a pair of substratal structures is drawn in separately an exploded, or separated, perspective view for easy-view viewing of the structure. However, they are contracted with each other in ~~real~~ actual use. The substratal structure means a structure including a plate-like support whose size is larger than the screen and at least another panel constituting member.

Please AMEND the paragraph beginning at page 6, line 4, as follows:

The plasma display panel 1 has a three-electrode surface discharge structure including

a first and a second main electrodes X, Y arranged in parallel that make an electrode pair for generating sustaining discharge, and an address electrode A as a third electrode that crosses the main electrodes X, Y in each cell (a display element). The main electrodes X, Y extend in the row direction (the horizontal direction) of the screen, and the second main electrode Y is used as a scanning electrode for selecting cells in a row for address. The address electrode A extends in the column direction (the vertical direction) and is used as a data electrode for selecting cells in a column. The area of the substrate surface where the main electrodes and the address electrodes cross each other corresponds to the screen ES.

Please AMEND the paragraph beginning at page 9, line 13, as follows:

In the manufacturing process of the front side substratal structure 10 explained above, after arranging the main electrodes X, Y on the glass substrate 11, photosensitive glass paste is coated thereon that includes crystallization glass as a main component and dark color pigments. The coat layer is patterned by photolithography process so as to make the colored paste layer 180 like a grid in the plan view. The, the low melting point glass paste without a coloring agent is coated as a non-colored paste layer 160 on the colored paste layer 180. Thus, the multilayer structure 145 made of the colored paste layer 180 and the non-colored paste layer 160 is formed on the glass substrate 11 as shown in Fig. 5A. The glass material is selected so that the softening point of the low melting point glass is set to relatively low temperature (e.g., 500 degrees centigrade). Then a crystallization glass is used that is crystallized at the temperature lower than the softening point of the low melting point glass.

Please AMEND the paragraph spanning pages 9-10, as follows:

The multilayer structure 145 is heated from the room temperature to the temperature (e.g., 590 degrees centigrade) that is substantially higher than the softening point of the low melting point glass for burning in appropriate temperature gradient, so that the colored glass layer 18 and the dielectric layer 48 16 are formed simultaneously as shown in Fig. 5B. Since the different difference between the softening point and the burning temperature is enlarged, defoaming and leveling of the surface are performed sufficiently, so that the dielectric layer 16 with high transparency can be obtained. In addition, since the colored paste layer 180 is crystallized and its viscosity is increased before the low melting point glass is softened, the

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pattern collapse of the colored paste layer 180 does not occur even if the viscosity of the low melting point glass is lower to approximately 10^3 PS after being heated to a sufficiently high temperature. In addition, the pigments do not diffuse into the non-colored paste layer 160, and the coloring of the dielectric layer 18 can be prevented.